L Number	Hits	Search Text	DB	Time stamp
1	2	("6313532").PN.	USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:05
2	73	inoue-kosuke.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/31 15:16
3	11	tenmei-hiroyuki.in.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:18
4	86	yamaguchi-yoshihide.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/31 15:20
6	36	hozoji-hiroshi.in.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:21
7	118	Tsunoda-shigeharu.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/31 15:21
8	22	minagawa-madoka.in.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:22
9	36	kanda-naoya.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:22
13	31	ujiie-kenji.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:24
12	51	yajima-akira.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:25
11	397	nishimura-asao.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:26
5	13	oroku-noriyuki.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/07/31 15:32
10	159	anjo-ichiro.in.	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/31 15:34

			WODDE.	2002/07/21
14	13	257/777-783.ccls. and insulat\$4 and	USPAT; US-PGPUB;	2003/07/31 15:36
		protrus\$4 and inclin\$4	EPO; JPO;	15:36
			DERWENT;	
		457 (707 700 700 704 1	IBM_TDB USPAT;	2003/07/31
15	12		US-PGPUB;	15:37
		and protrus\$4 and inclin\$4		15:57
			EPO; JPO;	<u> </u>
			DERWENT;	
			<pre>IBM_TDB USPAT;</pre>	2003/07/31
16	12		US-PGPUB;	15:38
		and protrus\$4 and inclin\$4	EPO; JPO;	13.36
			DERWENT;	
			IBM TDB	
_		ASE (EDA ESO EED)	USPAT;	2003/07/31
17	6	257/734,759,773.ccls. and insulat\$4 and	US-PGPUB;	16:07
		protrus\$4 and inclin\$4	EPO; JPO;	10.07
			DERWENT;	
			IBM TDB	
		(insulat\$4 dielectric) with protrus\$4	USPAT;	2003/07/31
19	68	(insulat;4 dielectric) with protrus;4 with inclin;4	US-PGPUB;	15:44
		with inclin94	EPO; JPO;	13.11
			DERWENT;	
			IBM TDB	
	F070	(insulat\$4 dielectric) with inclin\$4	USPAT;	2003/07/31
20	5870	(Insulat)4 dielectric/ with incliny4	US-PGPUB;	15:44
			EPO; JPO;	10111
			DERWENT;	
			IBM TDB	
21	83	(insulat\$4 dielectric) with inclin\$4 and	USPAT;	2003/07/31
21	03	(bump ball) and (IC chip die)	US-PGPUB;	15:58
		(bump ball) and (to emp alo)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
22	33	257/734,759,773.ccls. and (insulat\$4	USPAT;	2003/07/31
22		dielectric) with protrus\$4	US-PGPUB;	16:39
		distribution production	EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
24	532	(insulat\$4 dielectric) with protrus\$4 and	USPĀT;	2003/07/31
1		inclin\$4	US-PGPUB;	16:48
		· ·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
25	633	257/\$.ccls. and (insulat\$4 dielectric)	USPAT;	2003/07/31
		with protrus\$4 and semiconductor	US-PGPUB;	16:50
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
26	12		USPAT	2003/07/31
		"4451326" "4466177" "4470874"		17:02
		"4481070" "4515652" "4539744"		
		"4543597" "4545852" "4594769").PN.		